



VMDSEMI

**VFSA010R110NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	11mΩ@10V	14A

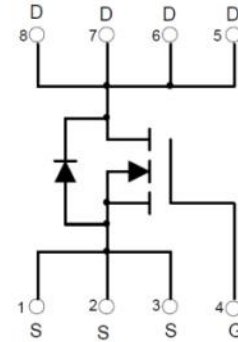


Figure 1 Symbol of VFSA010R110NA

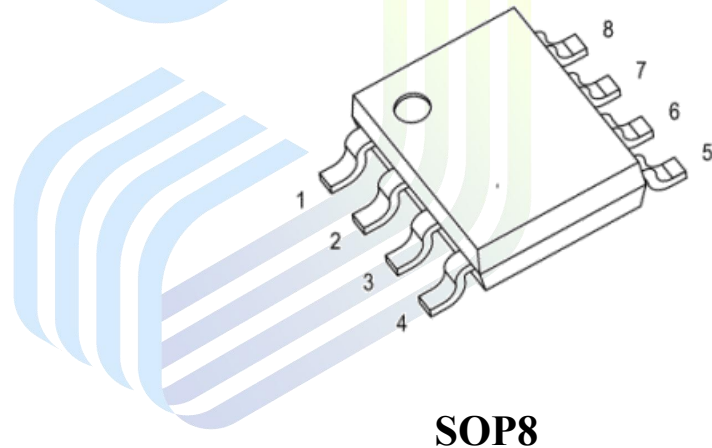
## Features

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

## Application

- Power Switch Application

## Package Type



## SOP8

Figure 2 Package Type of VFSA010R110NA

## Ordering Information

Product Name	Package
VFSA010R110NA	SOP8

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	14	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	56	
Avalanche Current <sup>Note3</sup>	$I_{AS}$	11	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	30	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	3.1	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		40		°C/W

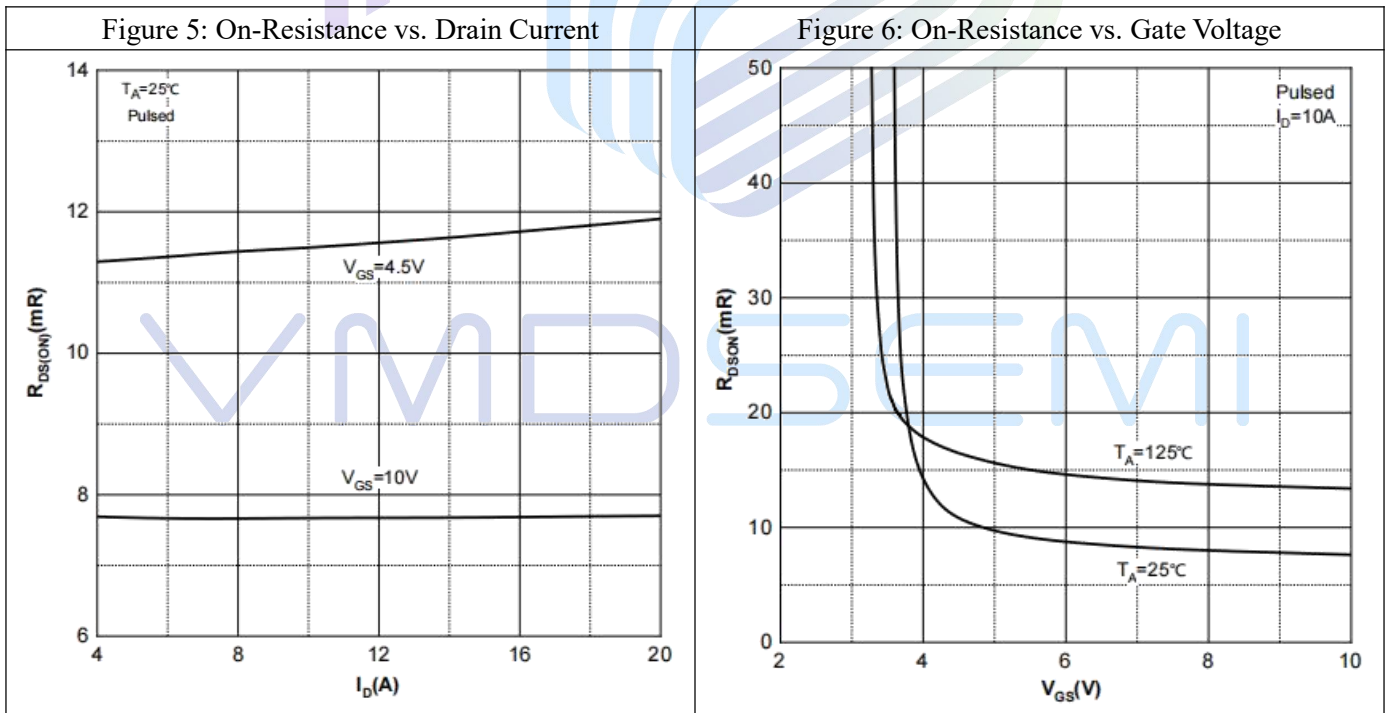
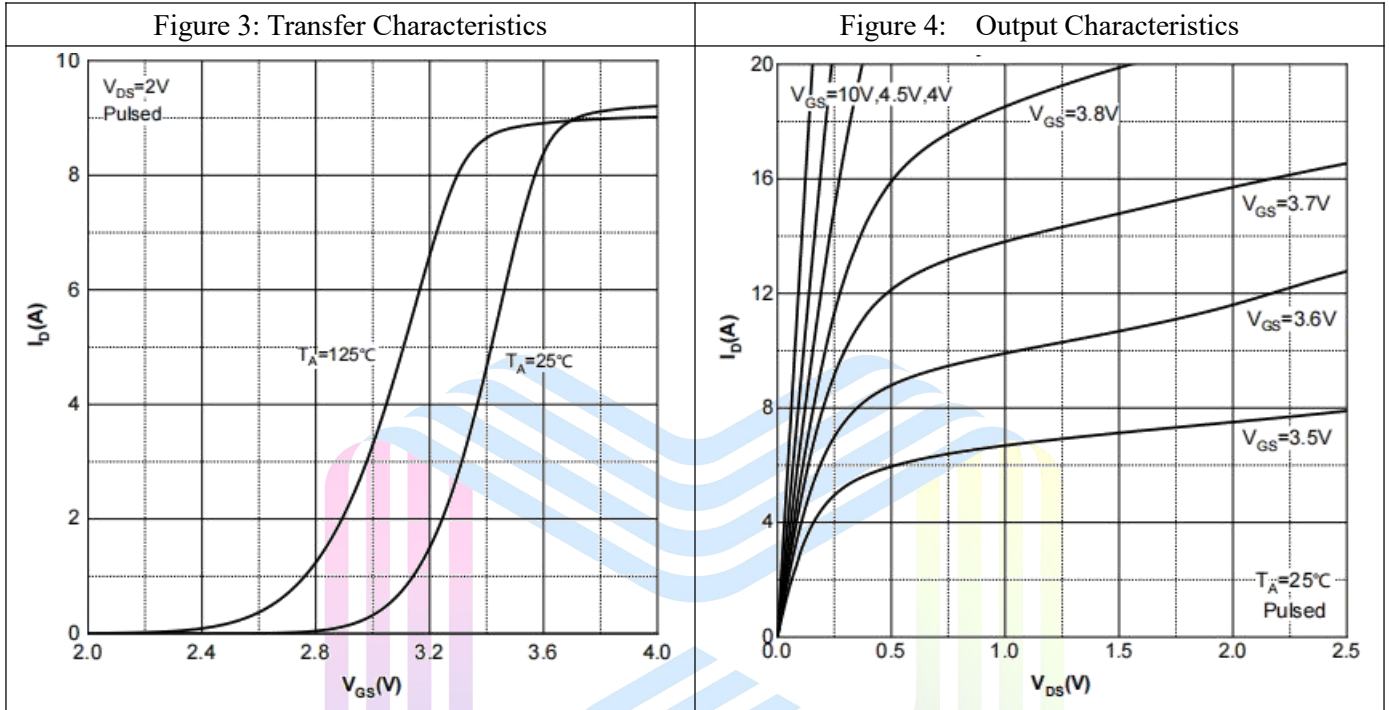


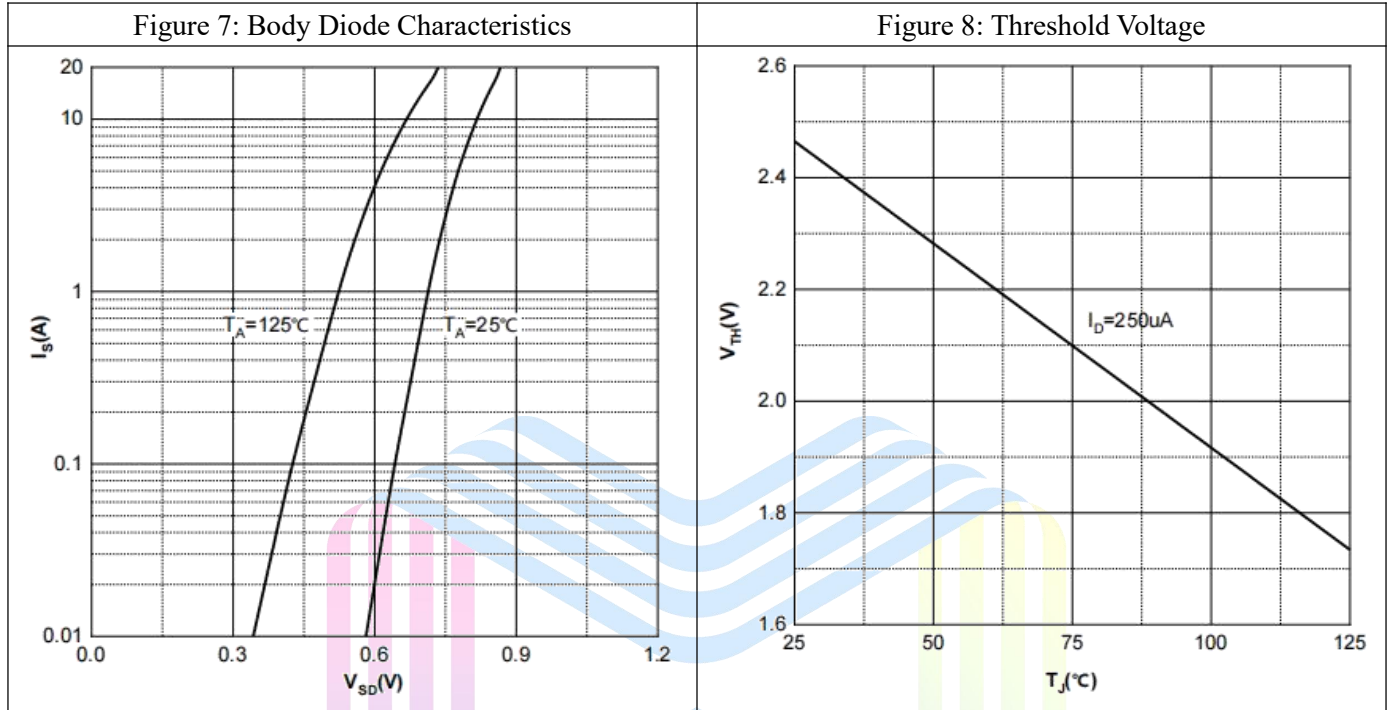
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	2.5	3.0	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		8	11	mΩ
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V$		1929		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		617		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		18		pF
Total Gate Charge	$Q_g$	$V_{DS}=50V$		39.8		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		7.1		
Gate-Drain Charge	$Q_{gd}$	$I_D=10A$		11.9		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.7		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		9		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		4		
Turn-off Delay Time	$t_{d(off)}$	$R_L=4.15\Omega$		25		
Turn-off Fall Time	$t_f$	$R_G=2.7\Omega$		4		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

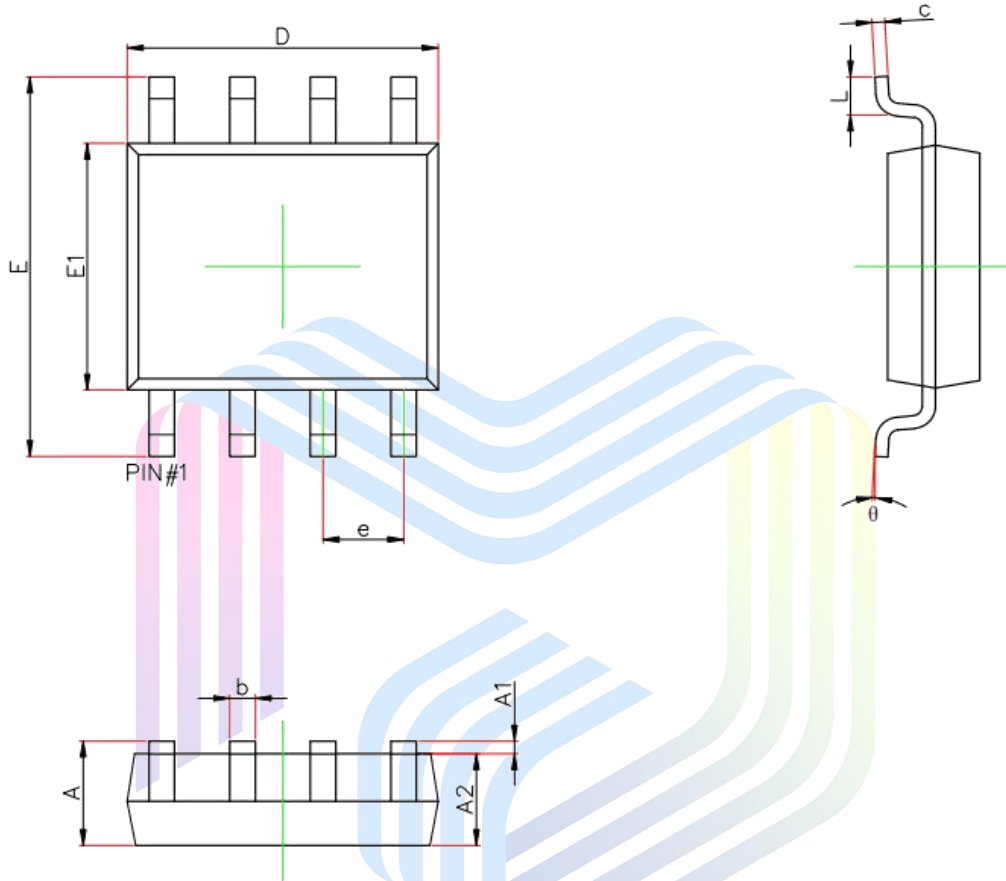
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
3. $E_{AS}$  condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$  Starting  $T_J = 25^\circ C$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ C$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ .

**Typical Performance Characteristics**




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**Mechanical Dimensions:**
**SOP8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.156	0.250	0.006	0.010
D	4.700	5.100	0.185	0.201
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
L	0.400	1.270	0.016	0.05
θ	0°	8°	0°	8°

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